

1     ABSTRACT OF THE DISCLOSURE

          A method of fabricating a semiconductor  
device includes a step of attaching a circuit  
substrate on a semiconductor wafer in alignment with  
5     each other, providing an electrical interconnection  
between the circuit substrate and semiconductor  
devices formed in the wafer, providing solder bumps on  
the circuit substrate, and dicing the semiconductor  
wafer together with the circuit substrate thereon  
10    along a scribe line.

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